

Integrated AMR for Cylinder Position Detection

DESCRIPTION

The TSHA2101 is produced with SIP (System in Package) technology which builds AMR sensor & ASIC in one IC. It supports both 2-wire & 3-wire applications for cylinder position detection.

The TSHA2101 is an AMR (Anisotropic Magneto Resistance) based magnetic sensor, when combined with a magnet, it becomes a non-contact switch with low power consumption, high sensitivity and high reliability device. A horizontal magnetic field parallel to the electrode of the package can be detected by an arbitrary polarity.

TSHA2101 can be used in both pull-up load and pull-down load applications.

FEATURES

- Omni-polar
- Supply voltage range 3.3V to 30V
- Operating frequency ≥4kHz
- -30V Reversed power supply protection
- Output over-current protection
- -40°C~105°C operating temperature
- Open-drain output with self-adaptation of Pull-up or Pull-down load (Equivalent loading ≤50k Ω @ 3-Wire)
- RoHS compliant
- Halogen-Free

APPLICATION

- 2-wire & 3-wire Cylinder position detection
- Pull-up & Pull-down load applications







TDFN2x3-6L



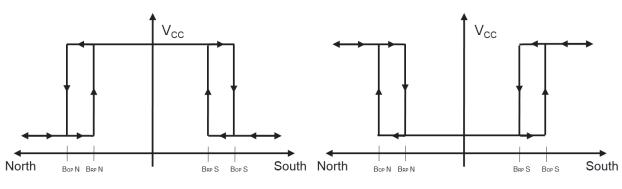
Pin Definition:

1. LED 6. OUT 2. LED 5. OUT 3. SEL 4. Vcc

Exposed pad connected to ground

Notes: MSL 1 (Moisture Sensitivity Level) per J-STD-020

DEFINITION OF SWITCHING FUNCTION



1

Pull-up load

Pull-down load





ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified) (Note)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Supply voltage	Vcc	-30 ~ 36	V		
Output current	Гоит	-500 ~ 500	mA		
Output voltage	V _{OUT}	-30 ~ 36	V		
LED output voltage	V _{LED}	-0.7 ~ 6	V		
SEL output voltage	V _{SEL}	-0.7 ~ 6	V		
Magnetic flux	В	3000	Gs		
Operating ambient temperature	T _A	-40 to +105	°C		
Storage temperature range	T _{STG}	-50 to +150	°C		
ESD rating (Human Body Mode)	HBM	±4.5	kV		
ESD rating (Charged Device Model)	CDM	±1	kV		

Note: Absolute maximum ratings are limited values to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability is not necessarily implied. Exposure to absolute maximum rating conditions for an extended period of time may affect device reliability. All voltages listed are referenced to GND.

ELECTRICAL SPECIFICATIONS (T _A = -40~105°C, V _{CC} = 3.3V~30V unless otherwise noted)							
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT	
Supply voltage		Vcc	3.3		30	V	
Supply current	Vcc=24V; B < Bor	Icc		60	100	μΑ	
Output saturation voltage	V _{CC} =24V; I _{OUT} =100mA; B > B _{OP} ; Pull-up load				0.5	V	
(3-wire)	Vcc=24V; Iout=-100mA; B > Bop ; Pull-down load	Vsat	V _{CC} - 0.5V;				
Output over-current protection	B > Bop ; Pull-up load	Іоср		200		- mA	
limit	B > Bop ; Pull-down load	1001		-200			
Output leakage current	B < B _{RP} ; V _{OUT} =24V; Dutput leakage current Pull-up load .				10		
(2-wire or 3-wire)	e or 3-wire) B < BRP ; Vcc=24V; Vout=0V;Pull-down load	-10			μA		
LED/SEL pin output current	B > Bop	I _{LED}	-0.8	-0.6	-0.4	mA	
Switching frequency		Fsw		4		kHz	
	V _{CC} =24V; C _L =100nf; Pull-down load, 2-wire	T_R			20	116	
Output rise time	Vcc=24V; C _L =1nf; Pull-up load, 3-wire	IR		10		μs	
Outrout fall time	V _{CC} =24V; C _L =100nf; Pull-up load, 2-wire	-			20		
Output fall time	V _{CC} =24V; C _L =1nf; Pull-up load, 3-wire	T _F			10	μs	
Power on time Refer to figure.17	Including Pull-up/Pull-down load detection time dVcc/dt>5V/µs	Тро			1	ms	
Output over-current protection delay time		Тосро			0.2	ms	
Output over-current protection recovery time		T _{OCPR}			200	ms	



ELECTRICAL SPECIFICATIONS (T _A = -40~105°C, V _{CC} = 3.3V~30V unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Over temperature protection point	Junction temperature	T _{OTPR}	1	140		°C
Over temperature recovery point	Junction temperature	Totrc		130		°C
	B _{OP} , T _A =25°C		±23	±31	±40	
Sensitivity L3	B _{RP} , T _A =25°C	Gs	±19	±26	±36	Gs
	B _{HYST} , T _A =25°C			4		

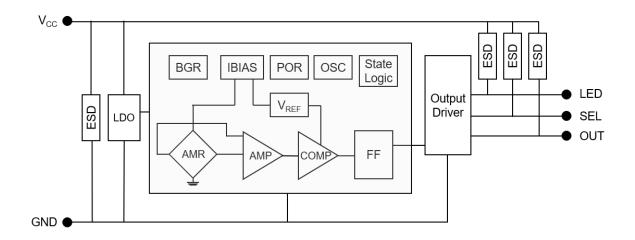
Note:

Magnetic operating/releasing point ($B_{OP}\&B_{RP}$) is configurable in applications (refer to Typical Application Circuit). We provide two options of $B_{OP}\&B_{RP}$ with different application circuit.

ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING		
TSHA2101CQ-L3 M3G	TDFN2x3-6L	3,000pcs / 7" Reel		

FUNCTION BLOCK

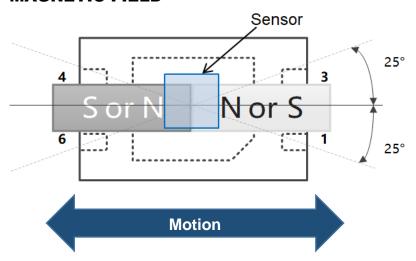


PIN DESCRIPTION

PIN NO.	NAME	FUNCTION
1	LED	LED driver output
2	LED	LED driver output
3	SEL	Magnetic Sensitivity Selection
4	Vcc	Supply voltage
5	OUT	Output
6	OUT	Output
Expos	ed Pad	Ground



DETECTION OF MAGNETIC FIELD



The device is sensitive to the magnetic field that is parallel to the package.

FUNCTION DESCRIPTION

- Bop: Operating Point, Magnetic flux density applied on the branded side of the package which turns the output driver ON (Vout=Low, pull-up load; Vout=High, pull-down load)
- BRP: Releasing Point, Magnetic flux density applied on the branded side of the package which turns the output driver OFF (Vout=High, pull-up load; Vout=Low, pull-down load)

4

BHYST: Hysteresis Window, |BOP - BRP|

CHARACTERISTICS CURVES

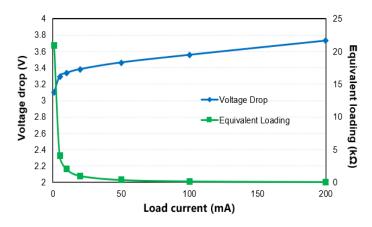


Figure 1. Voltage Drop vs. Loading Current (2-wire application)

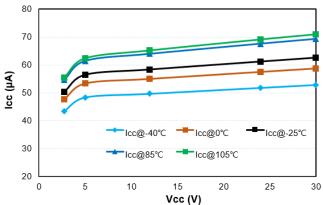


Figure 2. Supply Current vs. Temperature & Vcc



CHARACTERISTICS CURVES

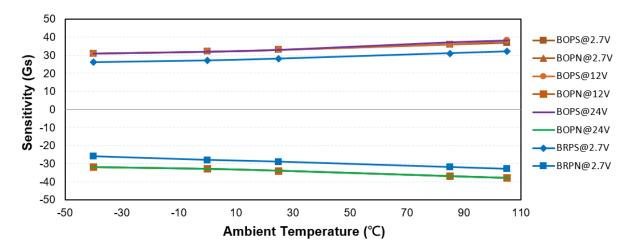
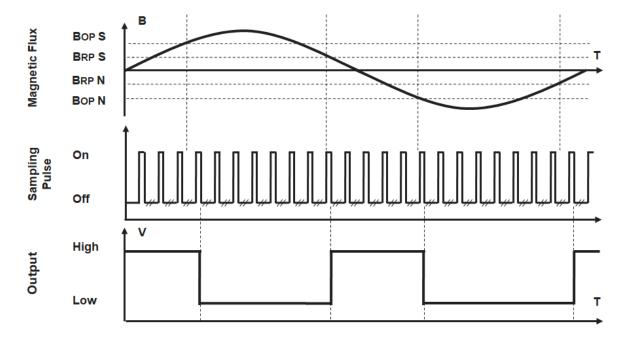


Figure 3. Magnetic Characteristics vs. Ambient Temperature & V_{CC} (B_{OP}& B_{RP})

TYPICAL OUTPUT WAVEFORM

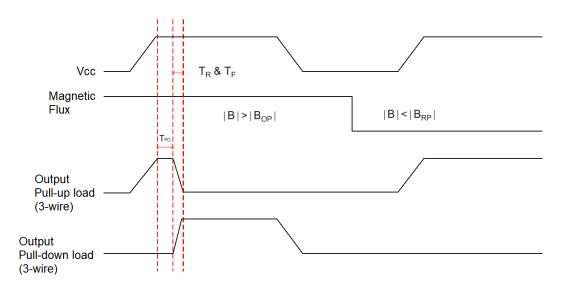


Digital Output vs. Magnetic Flux Density & Sampling Pulse (Pull-up load with 3-wire)



POWER ON OUTPUT WAVEFORM

 T_{PO} is the time from the stable point of V_{CC} to the valid point of output

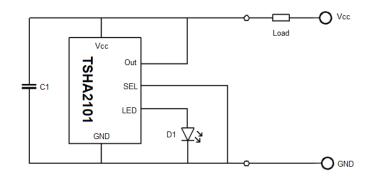


Power-On Output Waveform

TYPICAL APPLICATION CIRCUIT

SYMBOL	RECOMMEND
C1	0.1μF

2-Wire Applications



2-wire application circuit with Pull-up load

6



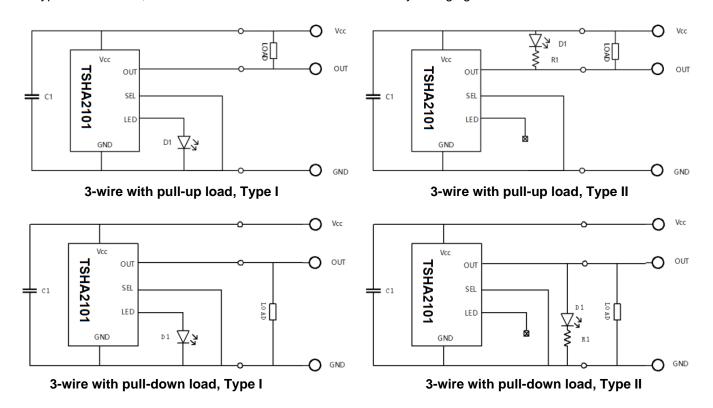
TYPICAL APPLICATION CIRCUIT

3-Wire Applications

For both pull-up and pull-down load in 3-wire applications, we recommend two kinds of connections, i.e. Type-I and Type-II

In Type-I connection, a constant current will be provided to D1.

In Type-II connection, user are allowed to tune the current of D1 by changing the value of R1

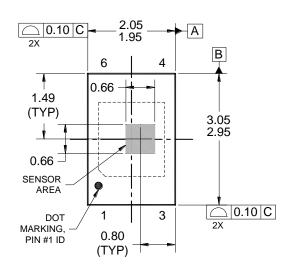


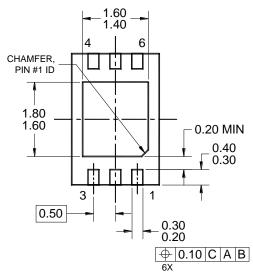
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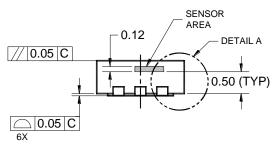


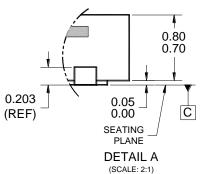
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

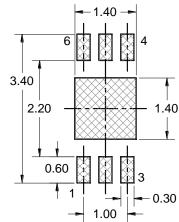
TDFN2x3-6L











DOT
MARKING
PIN #1 ID

1

XXXX
YWW
3

MARKING DIAGRAM
(TOP VIEW)

NOTES: UNLESS OTHERWISE SPECIFIED

SUGGESTED PAD LAYOUT

1. ALL DIMENSIONS ARE IN MILLIMETERS.

- DIMENSIONING AND TOLERANCING
 PER ASME Y14.5M-1994.
- 3. SEATING PLANE IS DEFINED BY TERMINAL BOTTOM SURFACE ONLY.
- 4. SUGGESTED PAD LAYOUT IS FOR REFERENCE PURPOSE ONLY.
- 5. DWG NO. REF: HQ2SD07-TDFN2X3_6L-081 REV A

8

2101 = DEVICE CODE Y = YEAR CODE WW = WEEK CODE



Taiwan Semiconductor

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